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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN PATENT APPLICATION:
SERIAL NO: 09/904,306)
APPLICANTS: Peter R. Nuytkens et al.)
TITLE: Interconnect Circuitry,)
Multichip Module, And Methods For)
Making Them)
FILING DATE: July 12, 2001)
GROUP ART UNIT: 2811)
EXAMINER: Quang D. Vu)

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January 17, 2003

I, JACOB N. ERLICH, hereby certify that on this Jan. 17, 2003,
I am mailing this document by Express Mail to the Assistant
Commissioner for Patents, Washington, D.C. 20231, with

Express Mail Label No. EL 449601117 US

Signed: [Signature] Date: January 17, 2003

Honorable Commissioner of Patents and Trademarks
Washington, D.C. 20231

AMENDMENT IN RESPONSE TO
FIRST OFFICE ACTION

Dear Sir:

In response to the office action of July 17, 2002
issued in the above identified application (the "Office
Action"), please amend this application as follows:

IN THE SPECIFICATION

Please amend paragraph 90 to change substrate "114" to
substrate "115" so that it reads as follows: